



DIMENSIONAL REFERENCES			
REF.	MIN.	NOM.	MAX.
A	1.25	1.40	1.50
A1	0.35	0.40	0.45
A2	0.65	0.70	0.75
A3	0.32 REF		
D	14.80	15.00	15.20
D1	12.80 BSC		
E	14.80	15.00	15.20
E1	12.80 BSC		
b	--	0.4	--
e	0.8 BSC		
f	--	1.10	--
aaa	--	--	0.15
bbb	--	--	0.10
ddd	--	--	0.10
eee	--	--	0.15
fff	--	--	0.08
M	17		
N	256		
Pkg. Code: X25655-1, X25655-2			

**NOTES:**

- ALL DIMENSIONS ARE IN MILLIMETERS.
- 'e' REPRESENTS THE BASIC SOLDER BALL PITCH.
- 'M' REPRESENTS THE BASIC SOLDER BALL MATRIX SIZE. 'N' IS THE NUMBER OF ATTACHED SOLDER BALLS.
- 'b' IS MEASURABLE AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO THE PRIMARY DATUM  $\boxed{-C-}$ .
- PRIMARY DATUM  $\boxed{-C-}$  AND THE SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- THE PACKAGE SURFACE SHALL BE MATTE FINISH CHARMILLES 24 TO 27.
- THE OVERALL PACKAGE THICKNESS "A" ALREADY CONSIDERS COLLAPSE BALLS.
- REFERENCE JEDEC MO-205.
- MARKING SHOWN IS FOR PKG. ORIENTATION ONLY.
- ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbFREE (+) PKG. CODES.
- MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC #10-0131.

-DRAWING NOT TO SCALE-



TITLE:  
PACKAGE OUTLINE,  
256 BALLS CSBGA, 15x15x1.4 mm

APPROVAL	DOCUMENT CONTROL NO. 21-0446	REV. C	1/1
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